Guest editorial

EMPC-IMAPS Poland 2018 – Guest Editorial

The International Microelectronics and Packaging Society (IMAPS) Poland Chapter was established in September 1982. In the beginning, it was the ISHM-Poland Chapter and from the 1997 it became the IMAPS-Poland Chapter.

The IMAPS is a non-profit making organization whose aim is to spread knowledge relating to hybrid microelectronics; a key technology in the assembly and application of semiconductors, thin film circuits and printed circuit boards (PCBs) to form practical miniaturized electronic equipment. In 2008, the IMAPS joined with IEEE Components, Packaging and Manufacturing Technology (CPMT) Society, bringing into formation the IMAPS-CPMT organization.

The 42nd IMAPS Poland International Conference was held in Biały Dom Hotel near Gliwice and took place between 23 and 26 September 2018. This event was organized by the Silesian University of Technology. The scope of the Conference covered everything in electronics between the chip and the system. The conference was attended by 71 participants, including 14 guests from abroad. During the Conference, 15 invited lectures and 42 posters were presented. The conference was supported by six international journals indexed in Journal Citation Report database and one journal indexed in Scopus.

This year, as in the previous year, two young Scientists have been awarded winning the refund of the conference fee during the next IMAPS 2019 Poland Conference.

In the special issue of *Soldering and Surface Mount Technology*, six papers have been collected (one review and five research papers), covering the processes and procedures associated with soldering and assembly technology. All of them were subjected to the journal's regular reviewing procedure.

The first four papers by Illés *et al.*, Livovsky and Pietrikova; Krammer *et al*; and Alaya *et al.* refer to the different aspects related to vapour phase soldering technology.

The next paper of Krammer *et al.* is about numerical modeling of solder pastes viscosity.

In the last article, Sobolewski and Dziurdzia describe the thermal conductivity of macro solder joints with voids.

I would like to thank all the authors for their scientific work and contributions that have led to the development and publication of this special issue of *Soldering and Surface Mount Technology*. I hope that it will be of interest to readers of the journal and that it will help them to find novel solutions, contribute to the creation of new ideas and initiate many varied discussions about PCBs and related interconnect technologies. I believe that this branch of science could be effectively developed in the future.

Agata Skwarek

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